Silicon P-Channel MOS FET

HITACHI

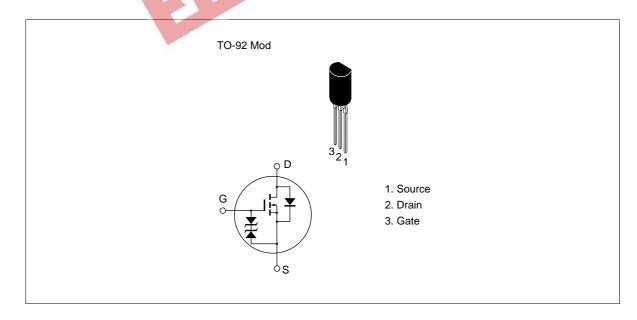
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- 4 V gate drive device can be driven from 5 V source
- 逐步^{表现。}Cn • Suitable for Switching regulator, DC - DC converter

Outline



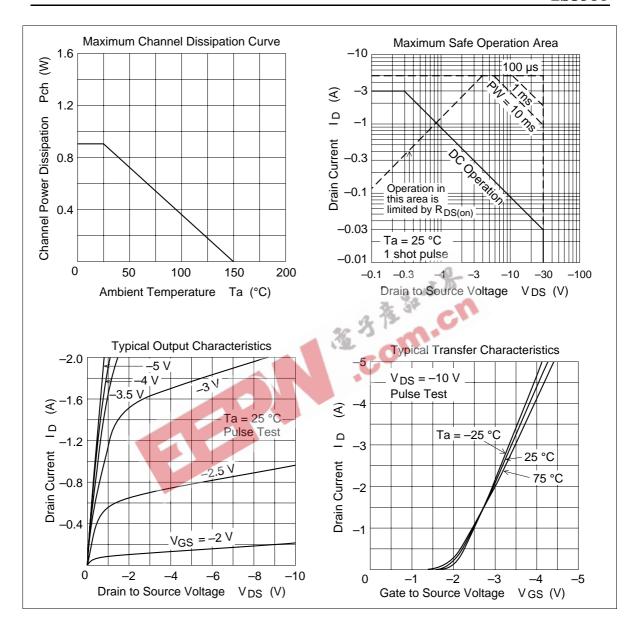


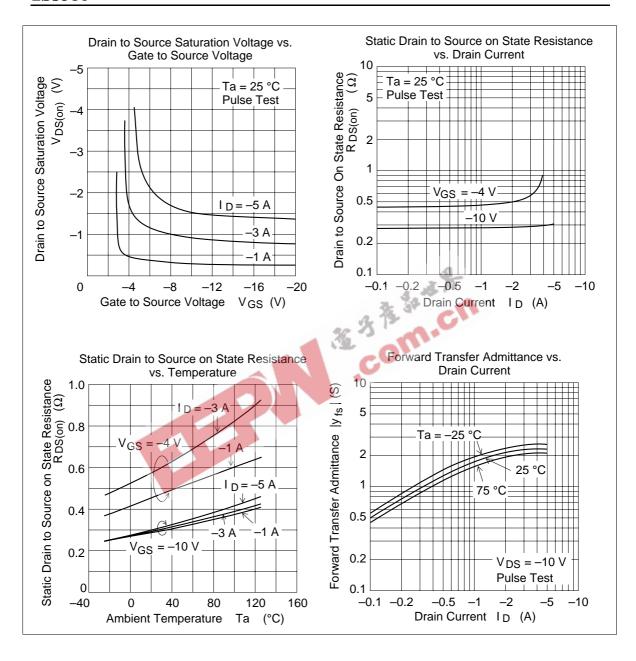
Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

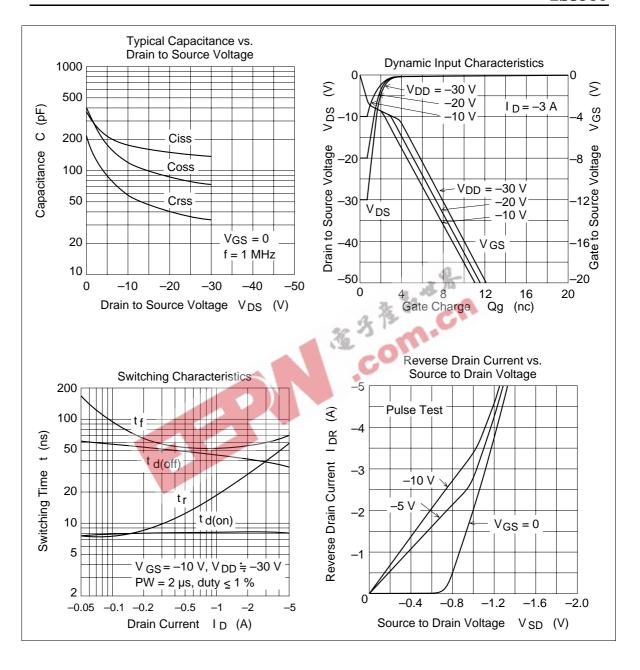
Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	-30	V
Gate to source voltage	V_{GSS}	±20	V
Drain current	I _D	-3	A
Drain peak current	*1 D(pulse)	- 5	A
Body to drain diode reverse drain current	I _{DR}	-3	А
Channel dissipation	Pch	0.9	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

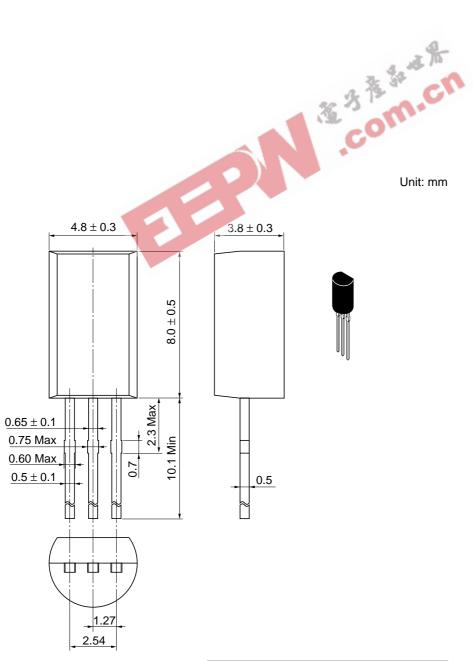
Electrical Characteristics (Ta = 25°C)

Note: 1. PW \leq 10 μ s, duty cycle \leq 1 %			2 %			
Electrical Characteristics (Ta = 25°C)			Typ Max Unit Test conditions			
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	-30	7		V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _{(BR)GSS}	±20	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	-10	μΑ	$V_{DS} = -24 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	-1.0	_	-2.5	V	$I_D = -1 \text{ mA}, V_{DS} = -10 \text{ V}$
Static drain to source on state resistance	R _{DS(on)}	_	0.3	0.4	Ω	$I_D = -2 A$ $V_{GS} = -10 V^{*1}$
		_	0.55	0.8	Ω	$I_D = -2 A$ $V_{GS} = -4 V^{*1}$
Forward transfer admittance	y _{fs}	1.0	1.7	_	S	$I_D = -1 A$ $V_{DS} = -10 V^{*1}$
Input capacitance	Ciss	_	177	_	pF	V _{DS} = -10 V
Output capacitance	Coss	_	120	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	59	_	pF	f = 1 MHz
Turn-on delay time	t _{d(on)}		8		ns	I _D = -2 A
Rise time	t _r	_	28	_	ns	$V_{GS} = -10 \text{ V}$
Turn-off delay time	t _{d(off)}	_	45		ns	$R_L = 15 \Omega$
Fall time	t _f	_	60	_	ns	









Hitachi Code	TO-92 Mod
JEDEC	_
EIAJ	Conforms
Weight (reference value)	0.35 g

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